

Multilayer Power Inductor

CIG21F Series (2012/ EIA 0805)

APPLICATION

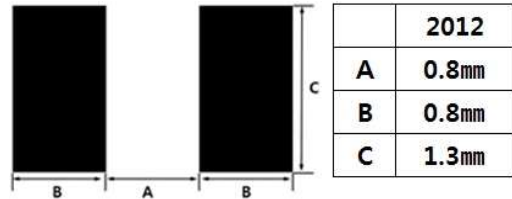
Mobile phones, DSC, DVC, PDA etc. for DC-DC Converter

FEATURES

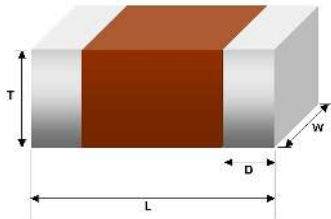
- Much lower Profile than any other series (0.5mm max)
- Low DC resistance
- Magnetically shielded structure
- Free of all RoHS-regulated substances
- Monolithic structure for high reliability



RECOMMENDED LAND PATTERN



DIMENSION



TYPE	Dimension [mm]			
	L	W	T	D
21	2.0±0.1	1.25±0.1	0.5max	0.5+0.2 -0.3

DESCRIPTION

Part no.	Size (inch/mm)	Inductance (uH)@1MHz	DC Resistance(Ω)	Rated Current (A) Max.
CIG21FR47MNC	0805/2012	0.47 ±20 %	0.12 ±25 %	1.10
CIG21F1R0MNC	0805/2012	1.0 ±20 %	0.19 ±25 %	0.80
CIG21F1R5MNC	0805/2012	1.5 ±20 %	0.25 ±25 %	0.70
CIG21F2R2MNC	0805/2012	2.2 ±20 %	0.34 ±25 %	0.60

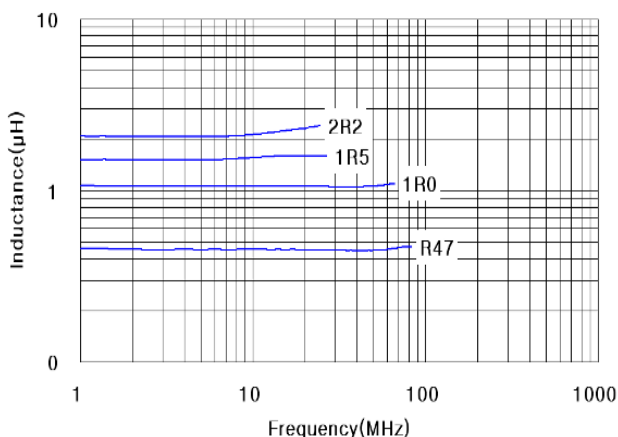
※Rated Current: DC current value when the self-generation of heat rises to 40℃ (Reference ambient temperature:25℃)

※Operating temperature range: -40 to +125℃ (Including self-temperature rise)

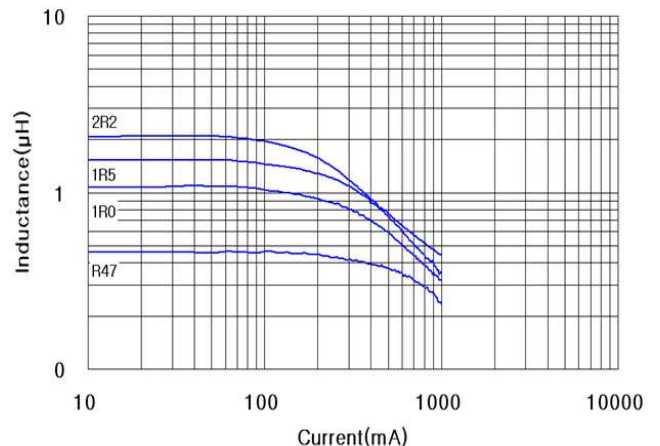
※Test equipment: Agilent :E4991A+16092A

CHARACTERISTIC DATA

1) Frequency characteristics (Typ.)



2) DC Bias characteristics (Typ.)



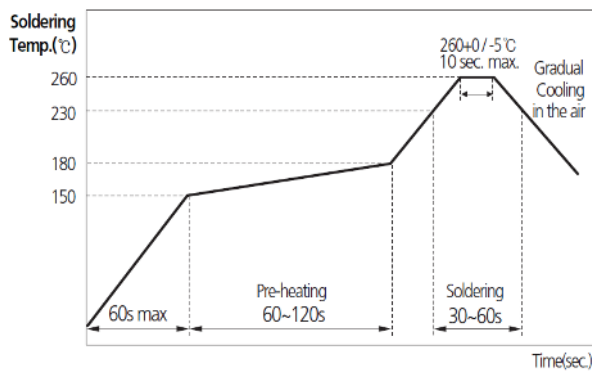
PRODUCT IDENTIFICATION

CI G 21 F 1R0 M N C
(1) (2) (3) (4) (5) (6) (7) (8)

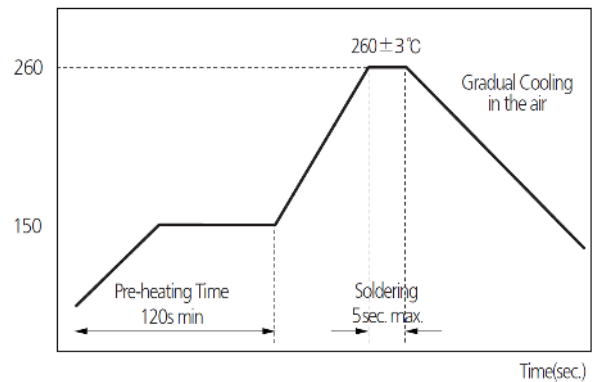
- (1) Chip Inductor
- (2) Power Inductor
- (3) Dimension
- (4) Product Series (F:Low Profile)
- (5) Inductance (R47:0.47uH, 1R0:1.0uH)
- (6) Tolerance (M:±20%)
- (7) Thickness option(N:Standard, A:Thinner than standard, B:Thicker than standard)
- (8) Packaging(C:paper tape, E:embossed tape)

RECOMMENDED SOLDERING CONDITION

REFLOW SOLDERING




FLOW SOLDERING



PACKAGING

Packaging Style	Quantity(pcs/reel)
Card Board Taping	4,000

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